


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	EMBEDDED PROCESSING/26/16334	
<b>1.3 Title of PCN</b>	TSHT (China) subcontractor additional back-end qualification for 32, 64 and 128Kb I <sup>2</sup> C EEPROM in SO8N	
<b>1.4 Product Category</b>	32, 64 & 128Kb I <sup>2</sup> C EEPROM in SO8N	
<b>1.5 Issue date</b>	2026-05-13	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	PIKE EMMA
<b>2.1.2 Phone</b>	+44 1628896111
<b>2.1.3 Email</b>	emma.pike@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	David RICETTO
<b>2.1.2 Marketing Manager</b>	Sylvain FIDELIS
<b>2.1.3 Quality Manager</b>	Mickael DENAIS-ALLICHON

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	N/A

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	As announced in PCN 16143, the present PCN is the second step for the introduction of TSHT (China) subcontractor as a second source for assembly & test site of the low densities EEPROM I <sup>2</sup> C 1Kb to 128Kb in SO8N (in CMOS F8H+ process technology).	This PCN is then concerning the 32Kb, 64Kb and 128Kb.
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	- Form: Marking change, dot at pin 1, no ejector mark at bottom side, appearance of the leads - Fit: No change - Function: No change	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	The strategy of the STMicroelectronics Memory division is to support our customers on products and service quality on a long-term basis. In line with this commitment, the qualification of the TSHT back-end assembly & test site as a second source will allow us to increase capacity and reinforce long term competitiveness. This PCN is coupled with matte Tin SO8N Shenzhen PCN (16335).
<b>5.2 Customer Benefit</b>	DOUBLE SOURCING

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	N/A
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2026-09-14
<b>7.2 Intended start of delivery</b>	2026-09-14
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	16334 RRCS2505 Reliability report F8H SO8N TSHT CuPd.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-05-13
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**9. Attachments (additional documentations)**

16334 Public product.pdf  
 16334 PCN TSHT 32 64 128 I2C F8H+.pdf  
 16334 RRCS2505 Reliability report F8H SO8N TSHT CuPd.pdf  
 16334 TERCS2026W16.pdf

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24128-BRMN6TP	
	M24C32-WMN6TP	

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